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FDS8935

# Dual P-Channel PowerTrench<sup>®</sup> MOSFET -80 V, -2.1 A, 183 m $\Omega$

#### **Features**

- Max  $r_{DS(on)}$  = 183 m $\Omega$  at  $V_{GS}$  = -10 V,  $I_D$  = -2.1 A
- $\blacksquare$  Max  $r_{DS(on)}$  = 247  $m\Omega$  at  $V_{GS}$  = -4.5 V,  $I_D$  = -1.9 A
- High performance trench technology for extremely low r<sub>DS(on)</sub>
- High power and current handling capability in a widely used surface mount package
- 100% UIL Tested
- RoHS Compliant

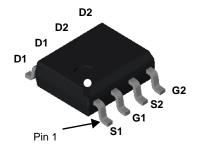


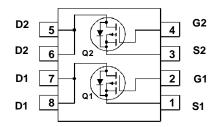
#### **General Description**

■ This P-channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been optimized for r<sub>DS(on)</sub>, switching performance and ruggedness.

#### **Applications**

- Load Switch
- Synchronous Rectifier





**SO-8** 

#### MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
V <sub>DS</sub>	Drain to Source Voltage			-80	V
$V_{GS}$	Gate to Source Voltage			±20	V
	Drain Current -Continuous			-2.1	^
'D	-Pulsed			-10	A
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	37	mJ
Б	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1a)	3.1	W
$P_{D}$	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1b)	1.6	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temper	erature Range		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	78	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS8935	FDS8935	SO-8	13 "	12 mm	2500 units

#### **Electrical Characteristics** T<sub>J</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-80			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, referenced to 25 °C		-61		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -64 V, V <sub>GS</sub> = 0 V			-1	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-1	-1.8	-3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, referenced to 25 °C		5		mV/°C
		$V_{GS} = -10 \text{ V}, I_D = -2.1 \text{ A}$		148	183	
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = -4.5 \text{ V}, I_D = -1.9 \text{ A}$		176	247	mΩ
, ,		$V_{GS} = -10 \text{ V}, I_D = -2.1 \text{ A}, T_J = 125 \text{ °C}$		249	308	
g <sub>FS</sub>	Forward Transconductance	$V_{DS} = -10 \text{ V}, I_{D} = -2.1 \text{ A}$		6.4		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 40.V V 0.V	661	879	pF
Coss	Output Capacitance	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	47	63	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 11/11/12	24	36	pF
R <sub>a</sub>	Gate Resistance		6		Ω

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		5	10	ns
t <sub>r</sub>	Rise Time	$V_{DD} = -40 \text{ V}, I_{D} = -2.1 \text{ A},$	3	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = -10 \text{ V}, R_{GEN} = 6 \Omega$	22	36	ns
t <sub>f</sub>	Fall Time		3	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V <sub>GS</sub> = 0 V to -10 V	13	19	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to -5 V}$ $V_{DD} = -40 \text{ V},$	7	10	nC
$Q_{gs}$	Gate to Source Charge	I <sub>D</sub> = -2.1 A	1.6		nC
$Q_{gd}$	Gate to Drain "Miller" Charge		2.6		nC

#### **Drain-Source Diode Characteristics**

V	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -2.1 \text{ A}$ (	Note 2)	-1.8	-1.3	V
v <sub>SD</sub>	7SD Source to Drain blode Forward voltage	$V_{GS} = 0 \text{ V}, I_{S} = -1.3 \text{ A}$ (	(Note 2)	-0.8	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = -2.1 A, di/dt = 300 A/μs		19	30	ns
Q <sub>rr</sub>	Reverse Recovery Charge	- I <sub>F</sub> = -2.1 A, αι/αι = 300 A/μs		34	54	nC
NOTES:	<u> </u>					

<sup>1.</sup> R<sub>0JA</sub> is determined with the device mounted on a 1in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0JC</sub> is guaranteed by design while R<sub>0CA</sub> is determined by the user's board design.



a)78 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b)135 °C/W when mounted on a minimun pad

<sup>2.</sup> Pulse Test: Pulse Width < 300 $\mu s$  , Duty cycle < 2.0%. 3. Starting T  $_J$  = 25 °C,  $\,$  L = 3.0 mH,  $I_{AS}$  = -5.0 A,  $V_{DD}$  = -80V,  $V_{GS}$  = -10V.

#### Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

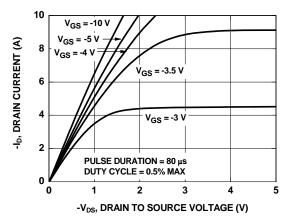


Figure 1. On-Region Characteristics

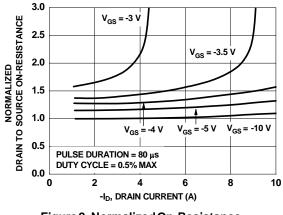


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

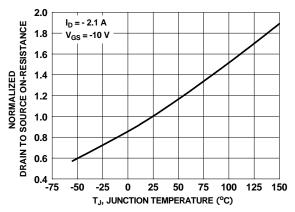


Figure 3. Normalized On-Resistance vs Junction Temperature

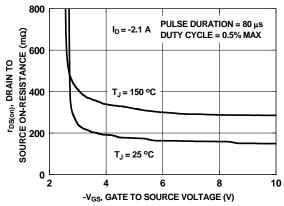


Figure 4. On-Resistance vs Gate to Source Voltage

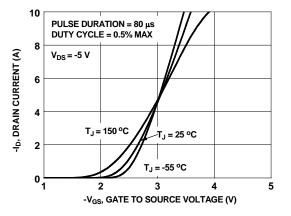


Figure 5. Transfer Characteristics

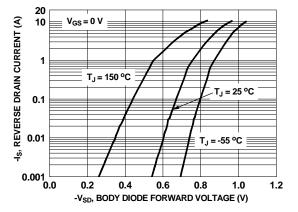


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

#### **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

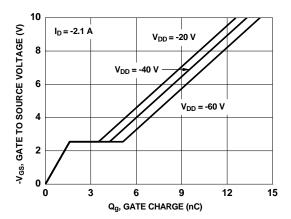


Figure 7. Gate Charge Characteristics

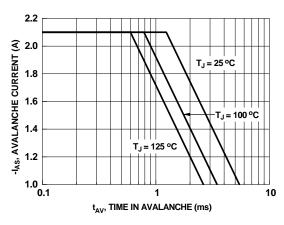


Figure 9. Unclamped Inductive Switching Capability

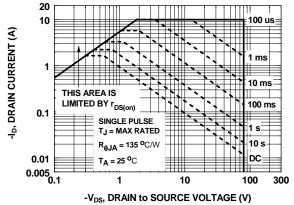


Figure 11. Forward Bias Safe
Operating Area

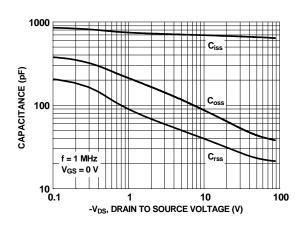


Figure 8. Capacitance vs Drain to Source Voltage

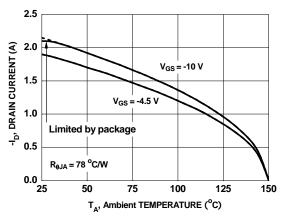


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

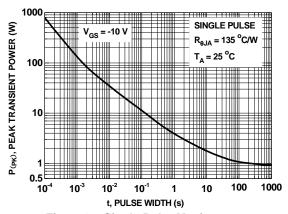


Figure 12. Single Pulse Maximum Power Dissipation

### **Typical Characteristics** T<sub>J</sub> = 25 °C unless otherwise noted

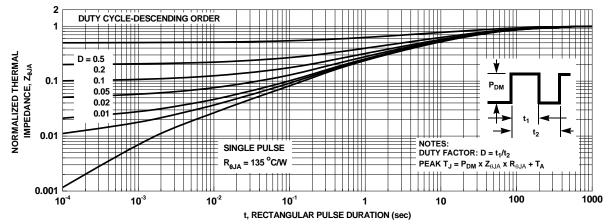


Figure 13. Junction-to-Ambient Transient Thermal Response Curve





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